



## Material Content Data Sheet



<b>Sales Product Name</b>		IPN60R600P7S		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA001973444						
<b>Package</b>		PG-SOT223-3-1		<b>Weight*</b>		116.64 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.664	1.43	1.43	14269	14269
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		135	
	non noble metal	iron	7439-89-6	0.052	0.04		449	
	non noble metal	copper	7440-50-8	52.304	44.84	44.89	448410	448994
	non noble metal	copper	7440-50-8	0.205	0.18	0.18	1758	1758
wire	non noble metal	copper	7440-50-8	0.205	0.18	0.18	1758	1758
encapsulation	organic material	carbon black	1333-86-4	0.177	0.15		1515	
	plastics	epoxy resin	-	6.890	5.91		59072	
	inorganic material	silicondioxide	60676-86-0	51.825	44.43	50.49	444302	504889
leadfinish	non noble metal	tin	7440-31-5	1.352	1.16	1.16	11592	11592
plating	noble metal	silver	7440-22-4	0.220	0.19	0.19	1890	1890
solder	non noble metal	tin	7440-31-5	0.039	0.03		332	
	noble metal	silver	7440-22-4	0.048	0.04		415	
	non noble metal	lead	7439-92-1	1.850	1.59	1.66	15861	16608
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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